

MATERIAL DECLARATION SHEET



Package Type	TBU-Pxxx		
Product Line	Semiconductor Products		
Compliance Date	January 1, 2008		
RoHS Compliant	Yes	MSL	1

No.	Construction Element (Subpart)	Homogeneous Material	Material Weight [g]	Homogeneous Material\ Substances	CAS Number if applicable	Materials Mass %	Material Mass % of Total Unit Weight	Subpart Mass of Total Wt. (%)
1	Encapsulation	Epoxy resin	0.04011	Epoxy Resin	Trade Secret	6	2.6937	44.896
				Phenol Resin	Trade Secret	3	1.3469	
				Silica fused	60676-86-0	90.45	40.6083	
				Carbon Black	1333-86-4	0.55	0.2469	
2	Leadframe	Copper alloy	0.04148	Copper	7440-50-8	96	44.5722	46.429
				Iron	7439-89-6	2.2	1.0214	
				Zinc	7440-66-6	0.1	0.0464	
				Phosphorous	7723-14-0	0.075	0.0348	
				Lead (impurity)	7439-92-1	0.001	0.0005	
				Silver (Plating)	7440-22-4	1.624	0.7540	
3	Chip	Silicon	0.00375	Silicon	7440-21-3	100	4.198	4.198
4	Die Attach	Conductive Silver Epoxy	0.00079	Silver	7440-22-4	93.4	0.8259	0.884
				Epoxy resin	Trade Secret	5.5	0.0486	
				Polymeric compound	Trade Secret	0.55	0.0049	
				Functionalized Ester	Trade Secret	0.55	0.0049	
5	Bond wires	Gold	0.00043	Gold	7440-57-5	99.99	0.4809	0.481
				Potential impurities may include Ag, Be or Ca ≤ 30 ppm	7440-22-4; 7440-41-7; 7440-70-2	0.01	0.0001	

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6	Terminal Finish	Alloy	00.0278	Tin	7440-31-5	100.00	3.112	3.112
		Total Weight	0.08934					

Updated January 29, 2019